



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE42994G			<b>Issued</b>	14. October 2015			
<b>MA#</b>	MA001302598							
<b>Package</b>	PG-DSO-8-16			<b>Weight*</b>	83.44 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	3.59	3.59	35898	35898
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8595	
wire	non noble metal	copper	7440-50-8	29.121	34.90	35.81	348994	358126
	noble metal	gold	7440-57-5	0.158	0.19	0.19	1891	1891
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1139
encapsulation	plastics	epoxy resin	-	4.371	5.24		52384	
	inorganic material	silicondioxide	60676-86-0	43.045	51.59	56.94	515865	569388
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9875	9875
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7793	7793
glue	plastics	acrylic resin	-	0.313	0.37		3746	
	noble metal	silver	7440-22-4	1.108	1.33	1.70	13283	17029
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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